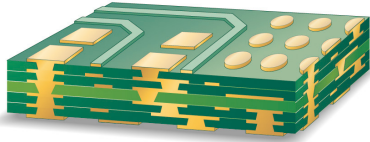


# High-density PWBs for SiP Modules



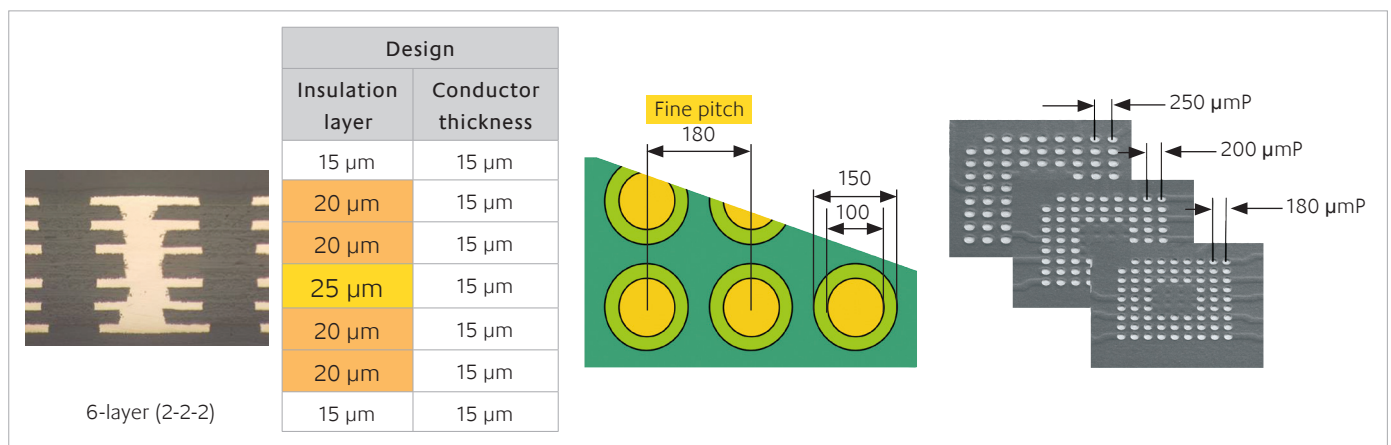
## FEATURES

- ▶ Laminates with high flexural modules and ultra-thin glass fiber
- ▶ High-density pads and patterning for accurate CSP assembly
- ▶ Thin and highly reliable PWBs
- ▶ 6-layer with 0.25 mm tickness - one of the thinnest in the market
- ▶ 180  $\mu\text{m}$  pitch pads are available

## APPLICATIONS

- ▶ Camera modules
- ▶ Bluetooth modules
- ▶ Wireless LAN modules
- ▶ Automotive industry – anti-collision systems, mmWave radar systems, ECUs

AnyLayer structure adopts ultra-thin base material and corresponds to fine pitch CSP



## Standard design specifications

Item	Specifications
Layer of build-up (Max.)	3
L/S (Min.)	40/40 $\mu\text{m}$
Via hole / Via land (LVH)	75/150 $\mu\text{m}$
Thickness of core material (Min.)	0.025 mm

Item	Specifications
Thickness of insulation layer (Min.)	0.020 mm
Board thickness (1-2-1)	0.18 mm
Board thickness (2-2-2)	0.25 mm

Special specifications or fine specifications over standard design specifications available on enquiry.